



N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

V _{(BR)DSS}	R _{DS(ON)}	I _D T _A = 25°C		
201/	2Ω @ V _{GS} = 4V	270mA		
30V	3.2Ω @ V _{GS} = 2.5V	210mA		

Description and Applications

This new generation MOSFET has been designed to minimize the onstate resistance $(R_{DS(on)})$ and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

- Backlighting
- DC-DC Converters
- · Power management functions

Features and Benefits

- Low On-Resistance
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- Lead Free By Design/RoHS Compliant (Note 1)
- . ESD Protected up to 2kV
- "Green" Device (Note 2)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

- Case: SOT-523
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin annealed over Alloy 42 leadframe.
 Solderable per MIL-STD-202, Method 208
- Terminal Connections: See Diagram
- Weight: 0.002 grams (approximate)

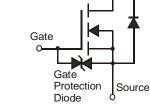
Drain

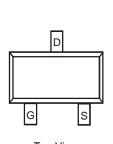




Top View

SOT-523





Equivalent Circuit

Top View Pin-Out

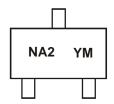
Ordering Information (Note 3)

Part Number	Case	Packaging
DMN313DLT-7	SOT-523	3000 / Tape & Reel

Notes:

- 1. No purposefully added lead.
- 2. Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com.
- 3. For packaging details, go to our website at http://www.diodes.com.

Marking Information



NA2 = Product Type Marking Code YM = Date Code Marking Y = Year (ex: X = 2010)

M = Month (ex: 9 = September)

Date Code Key

Year	201	0	2011		2012	20	13	2014		2015	2	2016
Code	X		Y		Z	A	A	В		С		D
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



Maximum Ratings @T_A = 25°C unless otherwise specified

Character	Symbol	Value	Unit		
Drain-Source Voltage	V _{DSS}	30	V		
Gate-Source Voltage			V _{GSS}	±20	V
Continuous Drain Current (Note 4) V _{GS} = 4.0V	Steady State	$T_A = 25$ °C $T_A = 70$ °C	I _D	0.27 0.21	А
Continuous Drain Current (Note 5) V _{GS} = 4.0V	Steady State	$T_A = 25$ °C $T_A = 70$ °C	I _D	0.31 0.25	А
Continuous Drain Current (Note 5) V _{GS} = 4.0V	t ≤ 10s	$T_A = 25$ °C $T_A = 70$ °C	I _D	0.38 0.3	А
Continuous Drain Current (Note 4) V _{GS} = 2.5V	Steady State	T _A = 25°C T _A = 70°C	I _D	0.21 0.15	А
Continuous Drain Current (Note 5) V _{GS} = 2.5V	t ≤ 10s	T _A = 25°C T _A = 70°C	I _D	0.29 0.22	А
Pulsed Drain Current (Note 6)			I _{DM}	1.2	Α

Thermal Characteristics

Characteristic	Symbol	Max	Unit
Power Dissipation (Note 4)	P _D	0.28	W
Thermal Resistance, Junction to Ambient @T _A = 25°C (Note 4)	$R_{\theta JA}$	474	°C/W
Power Dissipation (Note 5)	P _D	0.36	W
Thermal Resistance, Junction to Ambient @T _A = 25°C (Note 5)	R _{0JA}	361	°C/W
Power Dissipation (Note 5) t ≤ 10s	P _D	0.52	W
Thermal Resistance, Junction to Ambient @T _A = 25°C (Note 5) t ≤ 10s	$R_{\theta JA}$	252	°C/W
Operating and Storage Temperature Range	T_{J}, T_{STG}	-55 to +150	°C

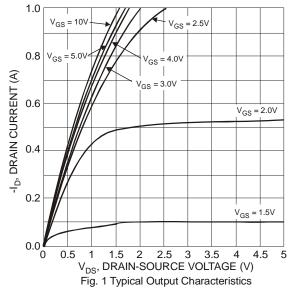
Electrical Characteristics @ T_A = 25°C unless otherwise stated

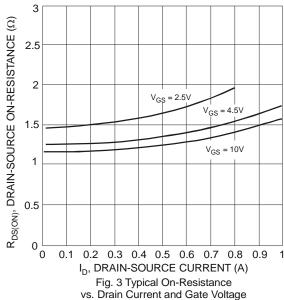
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						
Drain-Source Breakdown Voltage	BV _{DSS}	30	-	-	V	$V_{GS} = 0V, I_D = 250\mu A$
Zero Gate Voltage Drain Current T _J = 25°C	I _{DSS}	-	-	0.1	μΑ	$V_{DS} = 30V, V_{GS} = 0V$
Gate-Source Leakage	I _{GSS}	-	-	±1.0	μΑ	$V_{GS} = \pm 20V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 7)		-				
Gate Threshold Voltage	V _{GS(th)}	0.5	-	1.5	V	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$
Static Drain-Source On-Resistance	D	-	1.3	2	Ω	$V_{GS} = 4V, I_{D} = 10mA$
Static Drain-Source On-Resistance	R _{DS (ON)}	-	1.6	3.2		$V_{GS} = 2.5V, I_D = 1mA$
Forward Transfer Admittance	Y _{fs}	-	93	-	mS	$V_{DS} = 3V$, $I_D = 10mA$
Diode Forward Voltage	V _{SD}	-	0.7	1.3	V	$V_{GS} = 0V, I_{S} = 115mA$
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	C _{iss}	-	36.3	-)/ 5)/)/ O)/
Output Capacitance	Coss	-	7.6	-	pF	$V_{DS} = 5V, V_{GS} = 0V,$ f = 1.0MHz
Reverse Transfer Capacitance	C _{rss}	-	4.7	-		
Gate Resistance	Rg	-	128	-	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$
Total Gate Charge	Qg	-	0.5	-		
Gate-Source Charge	Q _{gs}	-	0.1	-	nC	$V_{GS} = 4.5V, V_{DS} = 15V,$ $I_{D} = 10mA$
Gate-Drain Charge	Q_{gd}	-	0.1	-		ID = TOTTIA
Turn-On Delay Time	t _{D(on)}	-	4.5	-	ns	151/11/151/
Turn-On Rise Time	t _r	-	2.24	-	ns	$V_{GS} = 4.5V, V_{DS} = 15V,$
Turn-Off Delay Time	t _{D(off)}	-	19.2	-	ns	$R_G = 2\Omega$,
Turn-Off Fall Time	t _f	-	28.2	-	ns	$I_D = 180 \text{mA}$

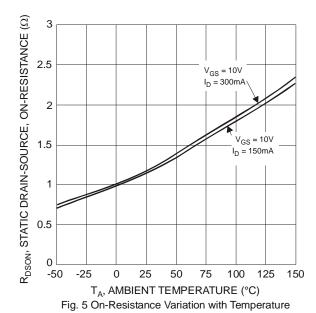
Notes:

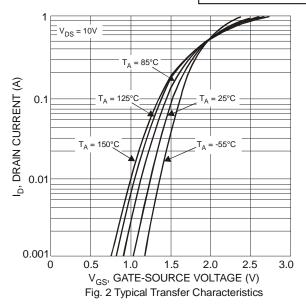
- 4. Device mounted on FR-4 PCB with minimum recommended pad layout, single sided.
- 5. Device mounted on 2" x 2" FR-4 PCB with high coverage 2 oz. Copper, single sided.
- Short duration pulse width limited by junction temperature.
 Short duration pulse test used to minimize self-heating effect.
- 8. Guaranteed by design. Not subject to production testing.

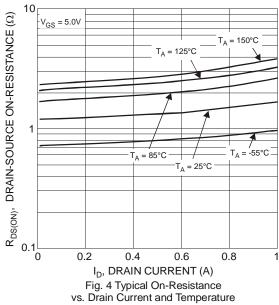












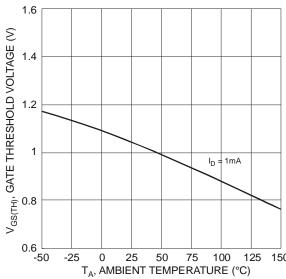
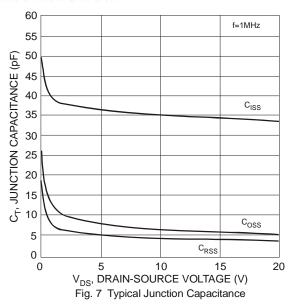
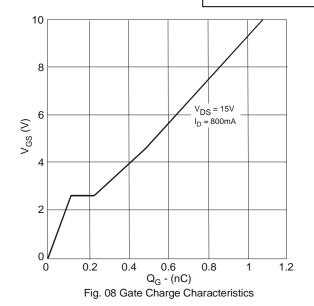


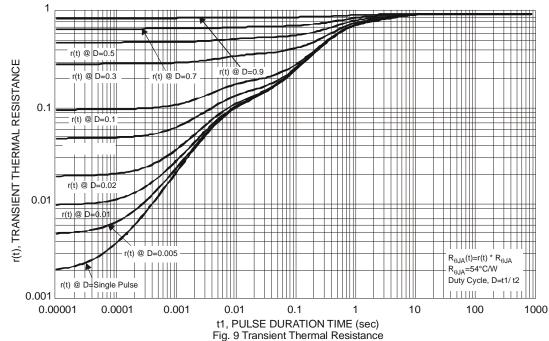
Fig. 6 Gate Threshold Variation vs. Ambient Temperature



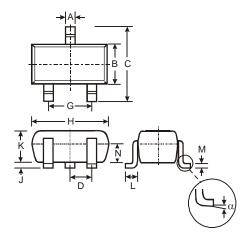
DMN313DLT







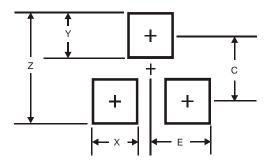
Package Outline Dimensions



SOT-523						
Dim	Min	Max	Тур			
Α	0.15	0.30	0.22			
В	0.75	0.85	0.80			
C	1.45	1.75	1.60			
D	_	_	0.50			
G	0.90	1.10	1.00			
Ι	1.50	1.70	1.60			
J	0.00	0.10	0.05			
K	0.60	0.80	0.75			
L	0.10	0.30	0.22			
М	0.10	0.20	0.12			
N	0.45	0.65	0.50			
α	0°	8°	_			
All Dimensions in mm						



Suggested Pad Layout



Dimensions	Value (in mm)
Z	1.8
Х	0.4
Υ	0.51
С	1.3
E	0.7

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